

Lead Industries Association, Inc.

292 Madison Avenue • New York, N. Y. 10017 • Telephone: (212) 679-6020

FEB 10 1975

February 6, 1975

SUBJECT: 4TH INTERNATIONAL AWS SOLDERING
CONFERENCE - CLEVELAND, OHIO
April 22-24, 1975

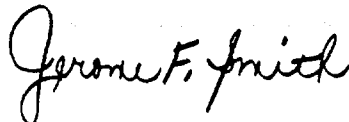
TO THE MEMBERS OF THE LEAD INDUSTRIES ASSOCIATION, INC.:

We would like to call to your attention that the LIA is co-sponsoring the Fourth International AWS Soldering Conference being held at the Cleveland Convention Center, Cleveland, Ohio, April 22, 23, 24, 1975.

Besides a series of formal presentations, there will also be two workshops in which individuals and organizations with questions about solder and the soldering process can discuss their problems with a panel of recognized experts.

A full program and advance registration form for the Welding Show and Conference is available upon request.

Sincerely,



Jerome F. Smith
Secretary & General Manager

JFS:ls
Attachment

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FOURTH INTERNATIONAL AWS SOLDERING CONFERENCE
Co-Sponsored by Lead Industries Association, Inc.

April 22, Tuesday Morning
9:30 A.M. to Noon

S-1. **ULTRASONIC SOLDERING**
Chairman, J. Terrill, Alcoa

Paper "A" - "Ultrasonic Soldering - A Production
Process of All Aluminum Coils"
J. L. Schuster and R. J. Chilko, Alcoa Laboratories

Paper "B" - "Fluxless Soldering Aluminum Air
Conditioner Coils"
W. B. Jenkins, Reynolds Metal Co.

Paper "C" - "Large Magnetostructure Ultrasonic
Soldering Pot for Fluxless Production Soldering"
R. L. Hunicke, Lewis Corporation

Paper "D" - "Ultrasonic Soldering of Joints"
J. N. Antonevich, Blackstone Corp.

Paper "E" - "Ultrasonic Soldering Equipment Used for
Aluminum Heat Exchangers"
C. A. Develow, Branson Sonic Power Co.

April 22, Tuesday Afternoon
2:00 to 4:30 P.M.

S-2. **WORKSHOP: ADVANCED TECHNIQUES IN BRAZING AND SOLDERING**
(Joint workshop of Fourth International AWS Soldering
Conference and Sixth International AWS-WRC Brazing
Conference)
J. R. Terrill, Chairman
(Participants and topics to be announced)

April 23, Wednesday Morning
9:30 A.M. to Noon

S-3. **DEVELOPMENTS IN SOLDERING MANUFACTURING TECHNOLOGY**

Chairman, W. G. Bader, Bell Telephone Laboratories
Co-Chairman, K. Smalberg, American Smelting &
Refining Company.

Paper "A" - "Automated Paste Soldering Developments"
J. J. McManus, Krohn, Inc.

Paper "B" - "Evaluation of Post Soldering Flux Removal"
Dr. J. Broos, Alpha Metals

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April 23, Wednesday Morning (Cont.)

Paper "C" - "Forced Hot Air Reflow of Solder Plated Printed Circuits"

A.M. Wittenbert, H. J. Schnelle, F.J. D'Erchia,
Bell Telephone Laboratories

Paper "D" - "Automatic Soldering and Brazing"

C. M. Norlin, Norbell Corp.

April 23, Wednesday Afternoon

2:00 to 4:30 P.M.

- S-4. WORKSHOP: FILLER METALS AND SOLDERS
(Joint Workshop of Fourth International AWS Soldering Conference and Sixth International AWS-WRC Brazing Conference)
Chairman, R. Beal, IIT Research Institute
Co-Chairman, R. L. Ray, Consultant
(Participants and topics to be announced).

April 24, Thursday Morning

9:30 A.M. to Noon

- S-5. NEW FLUX AND SOLDERING DEVELOPMENTS FROM RESEARCH

Chairman, J. F. Smith, Lead Industries Association
Co-Chairman, F. Barton, G. A. Avril Co.

Paper "A" - "High Lead Solder Alloy for Radiators"

R. Beal, IIT Research Institute

Paper "B" - "Lead Alloys for High Temperature Soldering of Magnet Wires"

W. Bader, Bell Telephone Laboratories

Paper "C" - "Effect of Low Frequency Thermal Cycling on Solder Joints"

R. E. Beal, E. R. Bangs, IIT Research Institute

Paper "D" - "The Influence of Flux Substitute and Solder Composition on the Wetting of Solders"

J. Shipley, IBM Corp.

NOTE: FOURTH INTERNATIONAL SOLDERING CONFERENCE
Cleveland Convention Center
Cleveland, Ohio
April 22, 23, 24, 1975

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